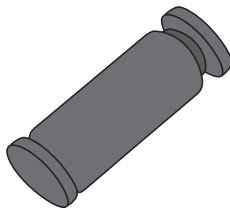


## Diac in MINIMELF package with tight $V_{BO}$



**MINIMELF**

### Features

- $V_{BO}$ : 32 V
- Low breakover voltage: 15  $\mu$ A max.
- Breakover voltage range: 30 to 34 V

### Applications

- General purpose AC line load switching
- Motor control circuits
- Home appliances
- Heating
- Lighting
- Inrush current limiting circuits
- Overvoltage crowbar protection

### Description

Functioning as a trigger diode with a fixed voltage reference, the **TMMDB3TG** can be used in conjunction with Triacs for simplified gate control circuits or as a starting element in fluorescent lamp ballasts.

#### Product status link

[TMMDB3TG](#)

#### Product summary

Order code	$V_{BO}$
TMMDB3TG	30 - 34 V

# 1 Characteristics

**Table 1. Absolute maximum ratings (limiting values),  $T_j = 25\text{ °C}$  unless otherwise specified**

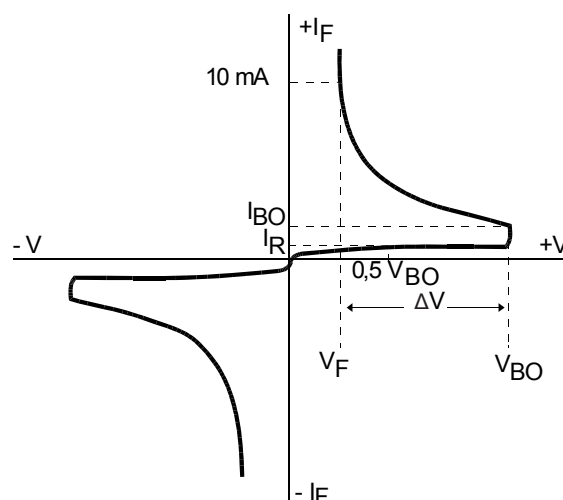
Symbol	Parameter	Value	Unit
$I_{TRM}$	Repetitive peak on-state current, $t_p = 20\text{ }\mu\text{s}$ , $F = 120\text{ Hz}$	2	A
$T_{stg}$	Storage junction temperature range	-40 to +125	°C
$T_j$	Operating junction temperature range	-40 to +125	°C

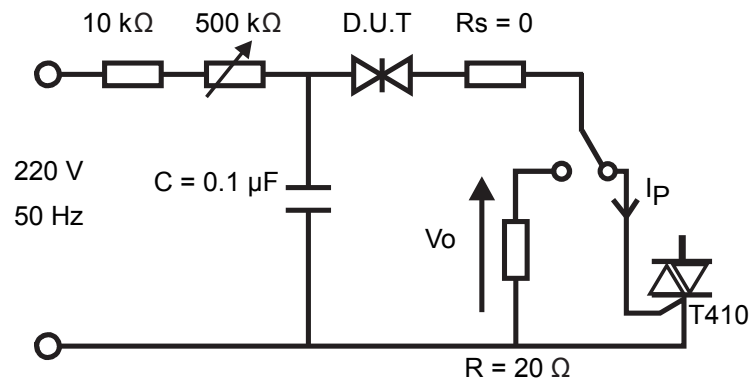
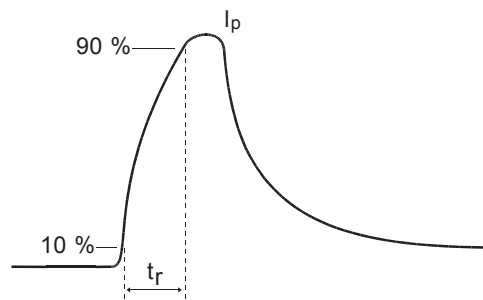
**Table 2. Electrical characteristics ( $T_j = 25\text{ °C}$  unless otherwise specified)**

Symbol	Parameter	Test conditions		Value	Unit
V <sub>BO</sub>	Breakover voltage <sup>(1)</sup>	C = 10 nF <sup>(2)</sup>	Min.	30	V
			Typ.	32	
			Max.	34	
V <sub>BO1</sub> - V <sub>BO2</sub>	Breakover voltage symmetry	C = 10 nF <sup>(2)</sup>	Max.	2	V
Δ V	Dynamic breakover voltage <sup>(1)</sup>	V <sub>BO</sub> and V <sub>F</sub> at 10 mA	Min.	9	V
V <sub>O</sub>	Output voltage <sup>(1)</sup>	See <a href="#">Figure 2. Test circuit</a> , (R = 20 Ω)	Min.	5	V
I <sub>BO</sub>	Breakover current <sup>(1)</sup>	C = 10 nF <sup>(2)</sup>	Max.	15	μA
t <sub>r</sub>	Rise time <sup>(1)</sup>	See <a href="#">Figure 3. Rise time measurement</a>	Max.	2	μs
I <sub>R</sub>	Leakage current <sup>(1)</sup>	V <sub>R</sub> = 0.5 x V <sub>BO</sub> max	Max.	10	μA
I <sub>P</sub>	Peak current <sup>(1)</sup>	See <a href="#">Figure 2. Test circuit</a>	Min.	0.30	A

1. Applicable to both forward and reverse directions.
2. Connected in parallel to the device

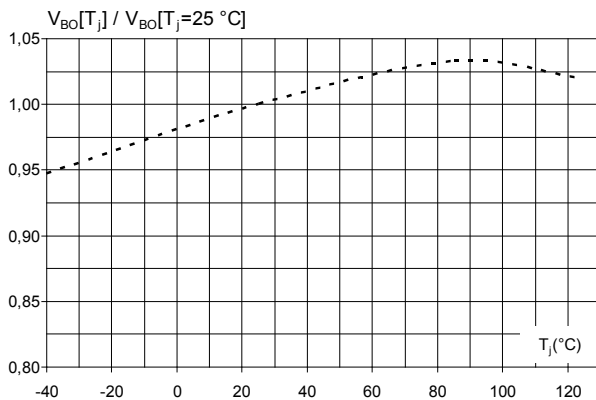
**Figure 1. Voltage - current characteristic curve.**



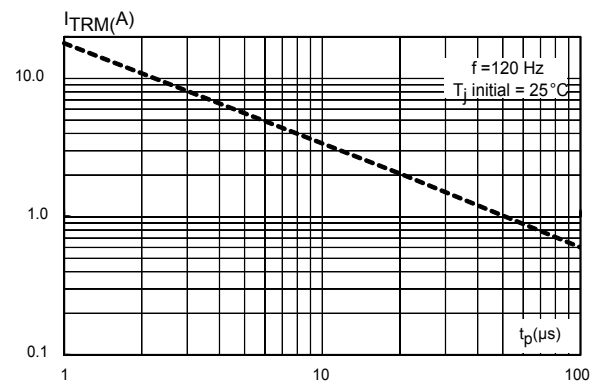
**Figure 2. Test circuit**

**Figure 3. Rise time measurement**


## 1.1 Characteristics (curves)

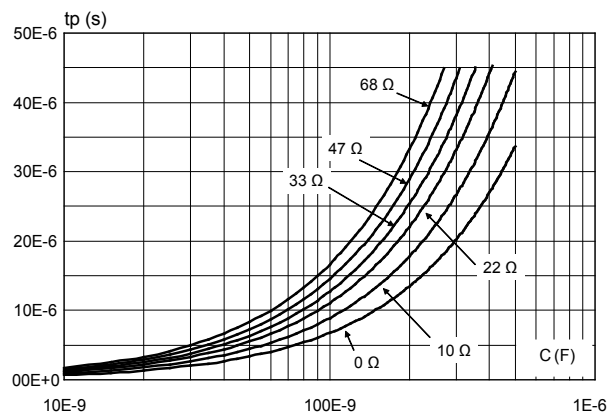
**Figure 4.** Relative variation of  $V_{BO}$  versus junction temperature (typical values)



**Figure 5.** Peak on-state current versus Triac gate current pulse duration  $t_p$



**Figure 6.** Triac gate current pulse duration  $t_p$  (to have  $I_p > 50$  mA) versus  $R_s$  and  $C$  values (typical values)



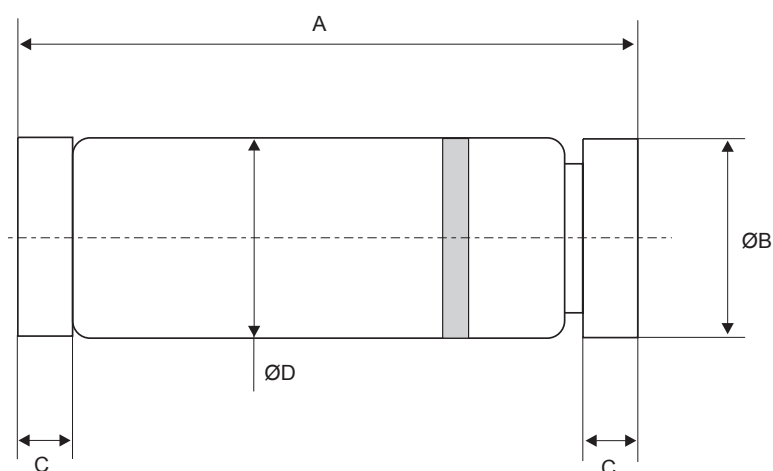
*Note:* according to Figure 2. Test circuit

## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 Minimelf package information

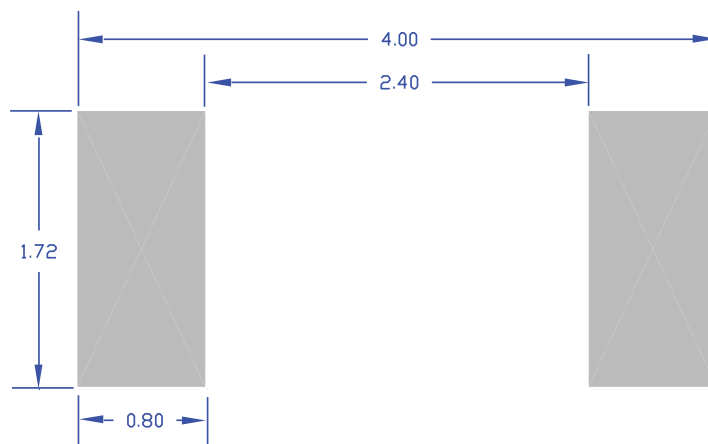
**Figure 7. MINIMELF package outline**



**Table 3. MINIMELF package mechanical data**

Dim.	mm					
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	3.30	3.50	3.70	0.130	0.138	0.146
B	1.59	1.65	1.70	0.063	0.065	0.067
C	0.40	0.50	0.60	0.016	0.020	0.024
D		1.50			0.059	

**Figure 8. MINIMELF recommended footprint (dimensions are in mm)**



### 3 Ordering information

Figure 9. Ordering information scheme

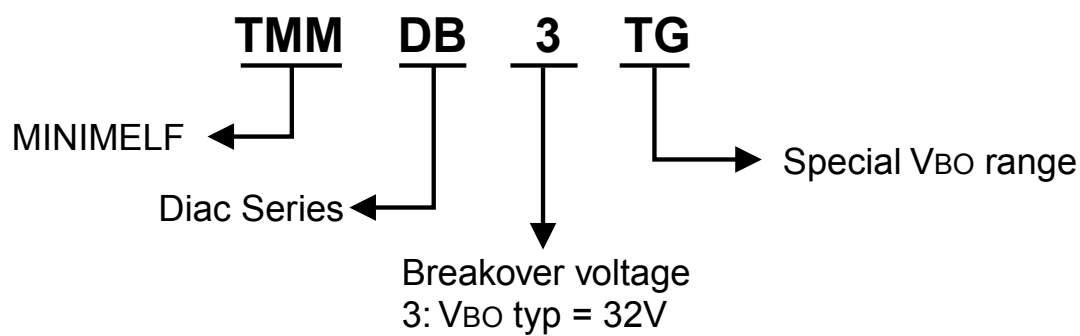


Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
TMMDB3TG	(None)	Minimelf	0.04 g	2500	Tape and reel

## Revision history

**Table 5. Document revision history**

Date	Version	Changes
January-2001	2	Previous release.
07-May-2019	3	Updated <a href="#">Section 1.1 Characteristics (curves)</a> and <a href="#">Table 3. MINIMELF package mechanical data</a> . Minor text change to improve readability.



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